

IN THE SPECIFICATION:

Please amend the abstract as follows.

A package substrate is manufactured by electrolytically plating Au in a semi-additive manner without using any plating lead line. Such a package substrate includes a base substrate with a plurality of through holes, a first copper plated layer on portions of the base substrate and inner surfaces of the through holes, a plated pattern layer on the first copper plated layer, wire bonding pads on the plated pattern layer at an upper surface of the base substrate, the wire bonding pads including Au and not connected to a remnant of a plating lead line, solder ball pads on the plated pattern layer at a lower surface of the base substrate, the solder ball pads including Au and not connected to a remnant of a plating lead line, and a solder resist covering the base substrate and the plated pattern layer. ~~on-wire bonding pads and solder ball pads, and a method for manufacturing the package substrate. The method includes the steps of forming a first copper plated layer on a base substrate having through holes and inner surfaces of the through holes, coating a first resist over the first copper plated layer, partially removing the first resist, thereby exposing portions of the first copper plated layer respectively corresponding to regions where circuit patterns are to be plated, forming a second copper plated layer on the exposed portions of the first copper plated layer, stripping the first resist, coating a second resist over the resultant structure, and removing the second resist from regions where wire bonding pads and solder ball pads are to be formed, removing exposed portions of the first copper plated layer, forming the wire bonding pads and the solder ball pads, removing the second resist, removing exposed portions of the first copper plated layer, and coating a solder resist over all surfaces of the resultant structure, and removing portions of the solder resist respectively covering the wire bonding pads and the solder ball pads.~~

Please amend the paragraph beginning at page 22, line 2 as follows.

Figs. 11a and 11b are views illustrating respective line densities of the conventional package substrate and the package substrate according to the present invention. In the conventional package substrate shown in Fig. 11a, solder ball pads 72a formed at its package substrate 71 have a ball pad pitch A defined between the centers of adjacent ones thereof. In Fig. 11a, the reference numeral 73 denotes a plating lead line. In the package substrate of the present invention shown in Fig. 11b, solder ball pads ~~72a~~ 72b formed at its package substrate 71 have a ball pad pitch B defined between the centers of adjacent ones thereof. Referring to Figs. 11a and 11b, the ball pad pitch B is less than the ball pad pitch A by, for example, about 0.1 to 0.15 mm. That is, as compared to the conventional package substrate, the package substrate of the present invention can form an increased number of solder ball pads at the same area because it dispenses with the plating lead line 73 shown in Fig. 11a. Accordingly, an improvement in line density is achieved in accordance with the present invention.